

### Features

- Operating voltage: 2.0V~6.0V
- Operating current < 2mA at 3.0V, No load
- Standby current  $I_{VDD} < 2\mu A$ , no load
- Separate logic power supply and motor power supply
- Built-in thermal shutdown circuit
- Built-in H bridge control circuit
- Built-in spark killer diode
- Provides strong ESD (min. of 4KV) per pin
- 8-pin SOP package

### Applications

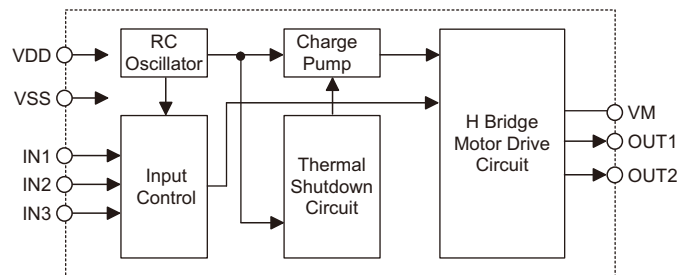
- Camera motor driver
- Toy motor driver

### General Description

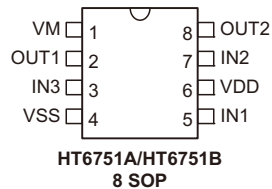
The IC can control H Bridge circuit for motor driving. It provides Spark Killer Diode/Thermal Shutdown function/Forward function/Reverse function/Brake func-

tion/Stop function for motor driver application. It is designed by LSI high technology with low power process.

### Block Diagram



### Pin Assignment



### Pin Description

Pin No.	Pin Name	I/O	Description
1	VM	P	Power of motor driving circuit
2	OUT1	O	Connect to motor terminal
3	IN3	I	Input signal
4	VSS	—	Negative power supply, ground
5	IN1	I	Input signal
6	VDD	—	Positive power supply
7	IN2	I	Input signal
8	OUT2	O	Connect to motor terminal

**Absolute Maximum Ratings**

Supply Voltage..... $V_{DD}$ -0.3V to 7.0V	Storage Temperature.....-40°C to 125°C
Voltage to Input Terminal.....-0.3V to $V_{DD}$ +0.3	Operating Temperature.....-20°C to 85°C
Junction Temperature.....150°C	

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

**Electrical Characteristics**
 $T_a=25^\circ\text{C}$ 

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
		$V_{DD}$	Conditions				
$V_{DD}$	Operating Voltage 1	—	—	2.0	—	6.0	V
$V_M$	Operating Voltage 2	—	Motor loading	1.8	—	6.0	V
$I_{VM}$	$V_M$ Current	5V	Standby mode with internal pump	—	—	10	$\mu\text{A}$
$I_{OPR}$	Operating Current	5V	No load @ $V_{DD}=5\text{V}$	—	—	2	mA
$I_{VDD}$	Standby Current	5V	Standby mode	—	1	2	$\mu\text{A}$
$I_{IL}$	Input Leakage Current	5V	$0 < V_{in} < V_{DD}$	-1.0	—	1.0	$\mu\text{A}$
$V_{IL}$	Input Low Voltage	5V	—	-0.3	—	$0.3V_{DD}$	V
$V_{IH}$	Input High Voltage	5V	—	$0.6V_{DD}$	—	$V_{DD}+0.3$	V
$R_{ON}$	H Bridge On Resistance	3V	(up_NMOS+down_NMOS) at 3V	—	—	0.4	$\Omega$
$t_{CP\_ON}$	Charge Pump Turn On Time	5V	$V_{DD}=V_M=5\text{V}$ , $I_{vm}=0.5\text{A}$	—	—	2	ms
$t_{CP\_OFF}$	Charge Pump Turn Off Time	5V	$V_{DD}=V_M=5\text{V}$ , $I_{vm}=0.5\text{A}$	—	—	1	ms
$t_{H\_ON}$	H Bridge Turn On Time	5V	$V_{DD}=V_M=5\text{V}$ , $I_{vm}=0.5\text{A}$	—	—	10	$\mu\text{s}$
$t_{H\_OFF}$	H Bridge Turn Off Time	5V	$V_{DD}=V_M=5\text{V}$ , $I_{vm}=0.5\text{A}$	—	—	5	$\mu\text{s}$

**Functional Description**

- In HT6751A function

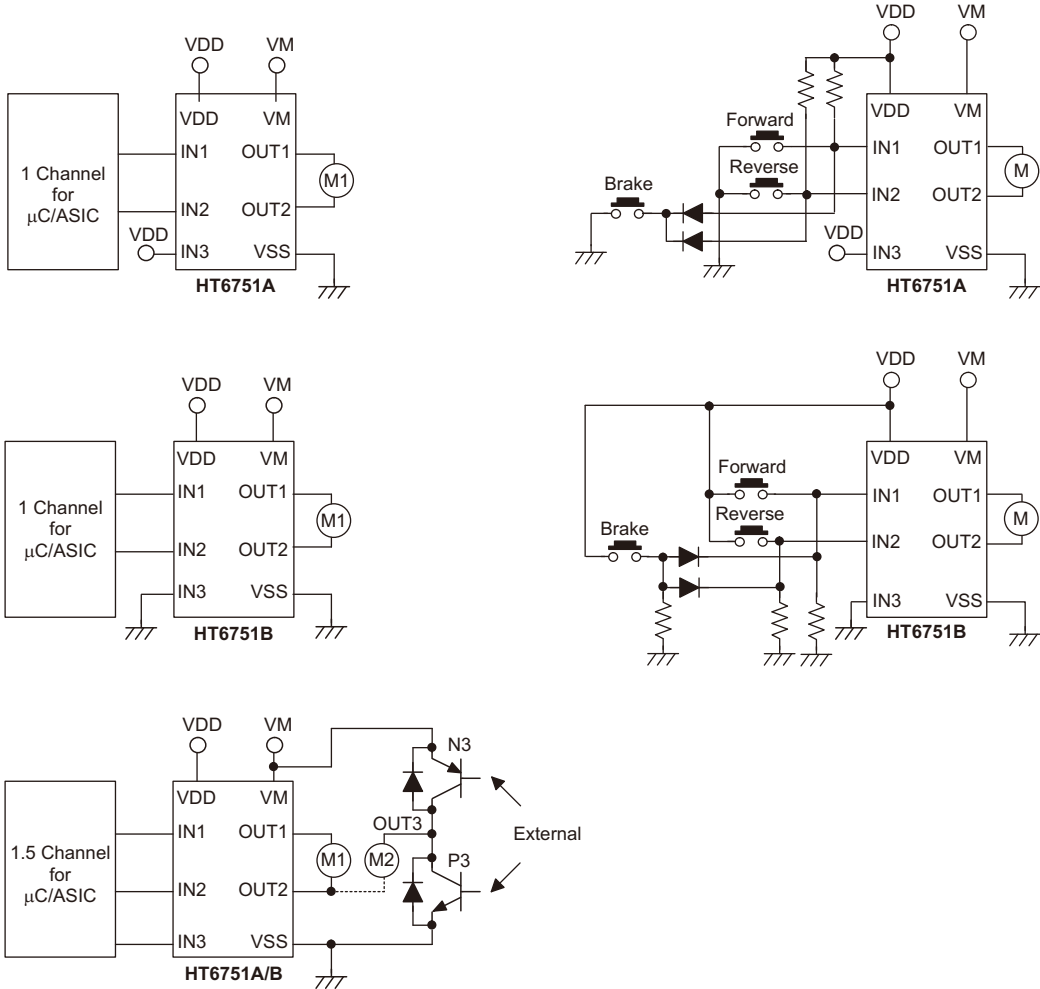
IN1	IN2	IN3	Function	MOS On	MOS Off
0	1	1	Motor1 forward	P1/N2	P2/N1
1	0	1	Motor1 reverse	P2/N1	P1/N2
0	0	1	Motor1 brake	N1/N2	P1/P2
1	1	1	Standby mode	—	P1/P2/N1/N2
0	1	0	Motor2 forward	P2/(N3)	N2/(P3)
1	0	0	Motor2 reverse	N2/(P3)	P2/(N3)
0	0	0	Motor2 brake	N2/(N3)	P2/(P3)

- In HT6751B function

IN1	IN2	IN3	Function	MOS On	Mos Off
1	0	0	Motor1 forward	P1/N2	P2/N1
0	1	0	Motor1 reverse	P2/N1	P1/N2
1	1	0	Motor1 brake	N1/N2	P1/P2
0	0	0	Standby mode	—	P1/P2/N1/N2
1	0	1	Motor2 forward	P2/(N3)	N2/(P3)
0	1	1	Motor2 reverse	N2/(P3)	P2/(N3)
1	1	1	Motor2 brake	N2/(N3)	P2/(P3)

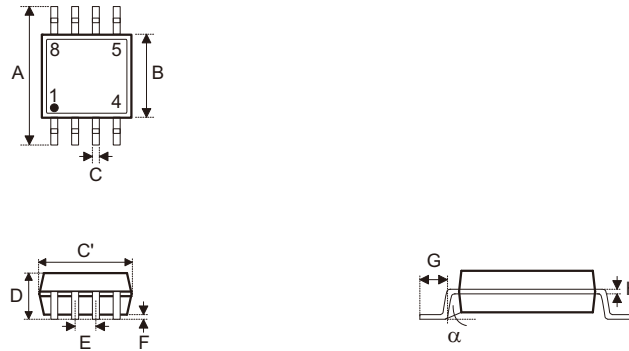
- ◆ In normal state and standby mode
  - Charge pump circuit is in off state
  - Oscillator circuit is in off state
  - Standby current is below 2 $\mu$ A
  - For HT6751A, the oscillator circuit and charge pump circuit is on until IN1 or IN2 or IN3 is low input
  - For HT6751B, the oscillator circuit and charge pump circuit is on until IN1 or IN2 or IN3 is high input
- ◆ The system enters thermal shutdown mode (current is limited below 500mA) when the temperature of the internal sensor is greater than Junction Temperature and then release this mode until the temperature of the internal sensor below (Junction Temperature >150°C). The system can accept IN1/IN2/IN3 signal when in thermal shutdown mode.

**Application Circuits**



**Package Information**

Note that the package information provided here is for consultation purposes only. As this information may be updated at regular intervals users are reminded to consult the Holtek website (<http://www.holtek.com.tw/english/literature/package.pdf>) for the latest version of the package information.

**8-pin SOP (150mil) Outline Dimensions**


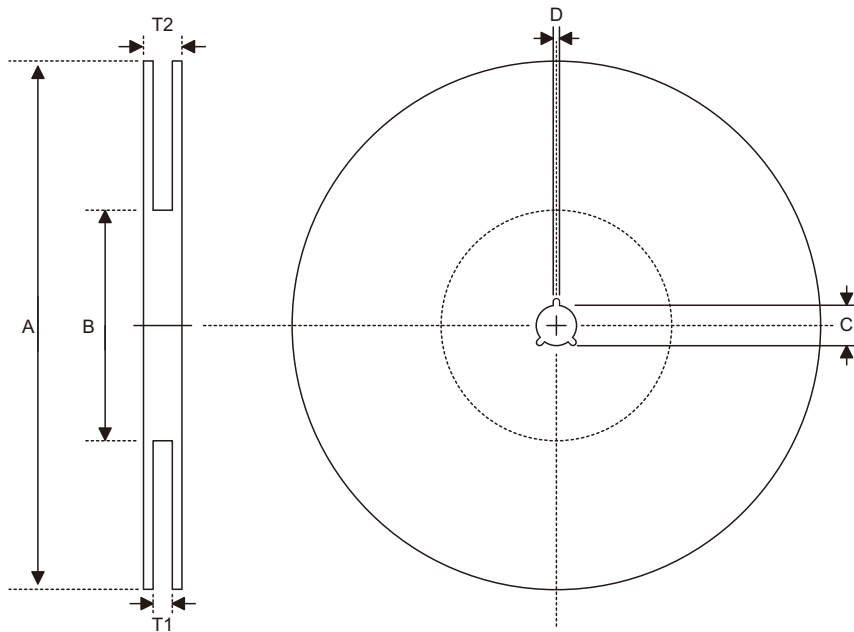
• MS-012

Symbol	Dimensions in inch		
	Min.	Nom.	Max.
A	0.228	—	0.244
B	0.150	—	0.157
C	0.012	—	0.020
C'	0.188	—	0.197
D	—	—	0.069
E	—	0.050	—
F	0.004	—	0.010
G	0.016	—	0.050
H	0.007	—	0.010
$\alpha$	0°	—	8°

Symbol	Dimensions in mm		
	Min.	Nom.	Max.
A	5.79	—	6.20
B	3.81	—	3.99
C	0.30	—	0.51
C'	4.78	—	5.00
D	—	—	1.75
E	—	1.27	—
F	0.10	—	0.25
G	0.41	—	1.27
H	0.18	—	0.25
$\alpha$	0°	—	8°

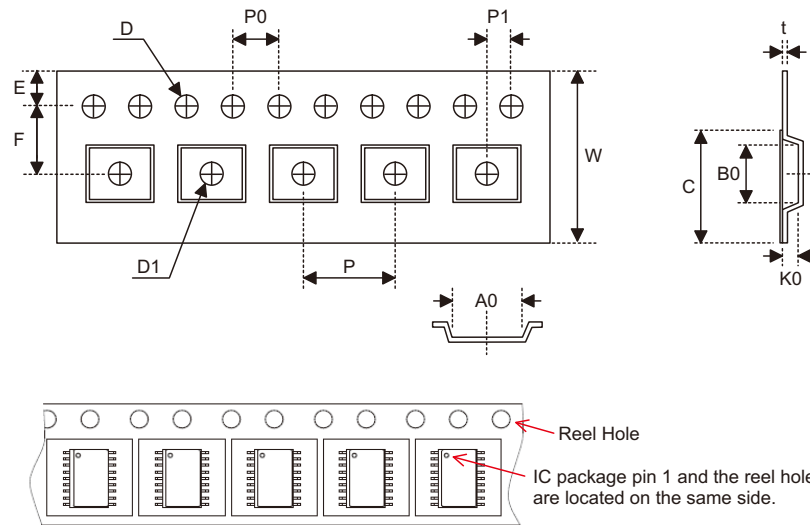
**Product Tape and Reel Specifications**

**Reel Dimensions**



SOP 8N

Symbol	Description	Dimensions in mm
A	Reel Outer Diameter	330.0±1.0
B	Reel Inner Diameter	100.0±1.5
C	Spindle Hole Diameter	13.0 <sup>+0.5/-0.2</sup>
D	Key Slit Width	2.0±0.5
T1	Space Between Flange	12.8 <sup>+0.3/-0.2</sup>
T2	Reel Thickness	18.2±0.2

**Carrier Tape Dimensions**

**SOP 8N**

Symbol	Description	Dimensions in mm
W	Carrier Tape Width	12.0 <sup>+0.3/-0.1</sup>
P	Cavity Pitch	8.0±0.1
E	Perforation Position	1.75±0.1
F	Cavity to Perforation (Width Direction)	5.5±0.1
D	Perforation Diameter	1.55±0.1
D1	Cavity Hole Diameter	1.50 <sup>+0.25/-0.00</sup>
P0	Perforation Pitch	4.0±0.1
P1	Cavity to Perforation (Length Direction)	2.0±0.1
A0	Cavity Length	6.4±0.1
B0	Cavity Width	5.2±0.1
K0	Cavity Depth	2.1±0.1
t	Carrier Tape Thickness	0.30±0.05
C	Cover Tape Width	9.3±0.1

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